Title (en)

HOUSING AND METHOD FOR ASSEMBLING THE HOUSING

Title (de)

GEHÄUSE UND VERFAHREN ZUR MONTAGE DES GEHÄUSES

Title (fr)

BOÎTIER ET PROCÉDÉ DE MONTAGE DU BOÎTIER

Publication

EP 2340695 A1 20110706 (DE)

Application

EP 08875238 A 20081028

Priority

EP 2008064583 W 20081028

Abstract (en)

[origin: WO2010048986A1] The invention relates to a housing for receiving a circuit board, comprising a first housing part having a first floor and a first side wall; comprising a second housing part having a second floor and a second side wall; wherein the first housing part comprises at least one catch protrusion in an area of at least one corner, said protrusion protruding past the first side wall; wherein the second housing part comprises a catch recess in the area of at least one corner. The invention further relates to a method for assembling the housing and to an assembly device.

IPC 8 full level

H05K 5/00 (2006.01)

CPC (source: EP KR US)

H05K 5/00 (2013.01 - KR); **H05K 5/0013** (2013.01 - EP US); **H05K 5/06** (2013.01 - KR); Y10T 29/49826 (2015.01 - EP US)

Citation (search report)

See references of WO 2010048986A1

Citation (examination)

JP H08162770 A 19960621 - YAZAKI CORP

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

WO 2010048986 A1 20100506; CN 102204422 A 20110928; EP 2340695 A1 20110706; JP 2012507159 A 20120322; JP 5762296 B2 20150812; KR 20110091701 A 20110812; US 2011203966 A1 20110825

DOCDB simple family (application)

EP 2008064583 W 20081028; CN 200880131727 A 20081028; EP 08875238 A 20081028; JP 2011533544 A 20081028; KR 20117012190 A 20081028; US 200813126763 A 20081028